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United States Patent [19]

Kobayashi et al.

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[54] **INTEGRATED CIRCUIT PACKAGE**

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[73] Assignees: **Citizen Electronics Co., Ltd.**; **Seiko Instruments Inc.**, both of Japan

[**] Term: **14 Years**

[21] Appl. No.: **29/093,046**

[22] Filed: **Sep. 2, 1998**

[51] **LOC (6) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/158, 182,
D13/184; D14/100, 114; 174/35 R, 50;
206/701, 706, 718; 257/678; 220/4.02

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Primary Examiner—Adir Aronovich
Attorney, Agent, or Firm—Adams & Wilks

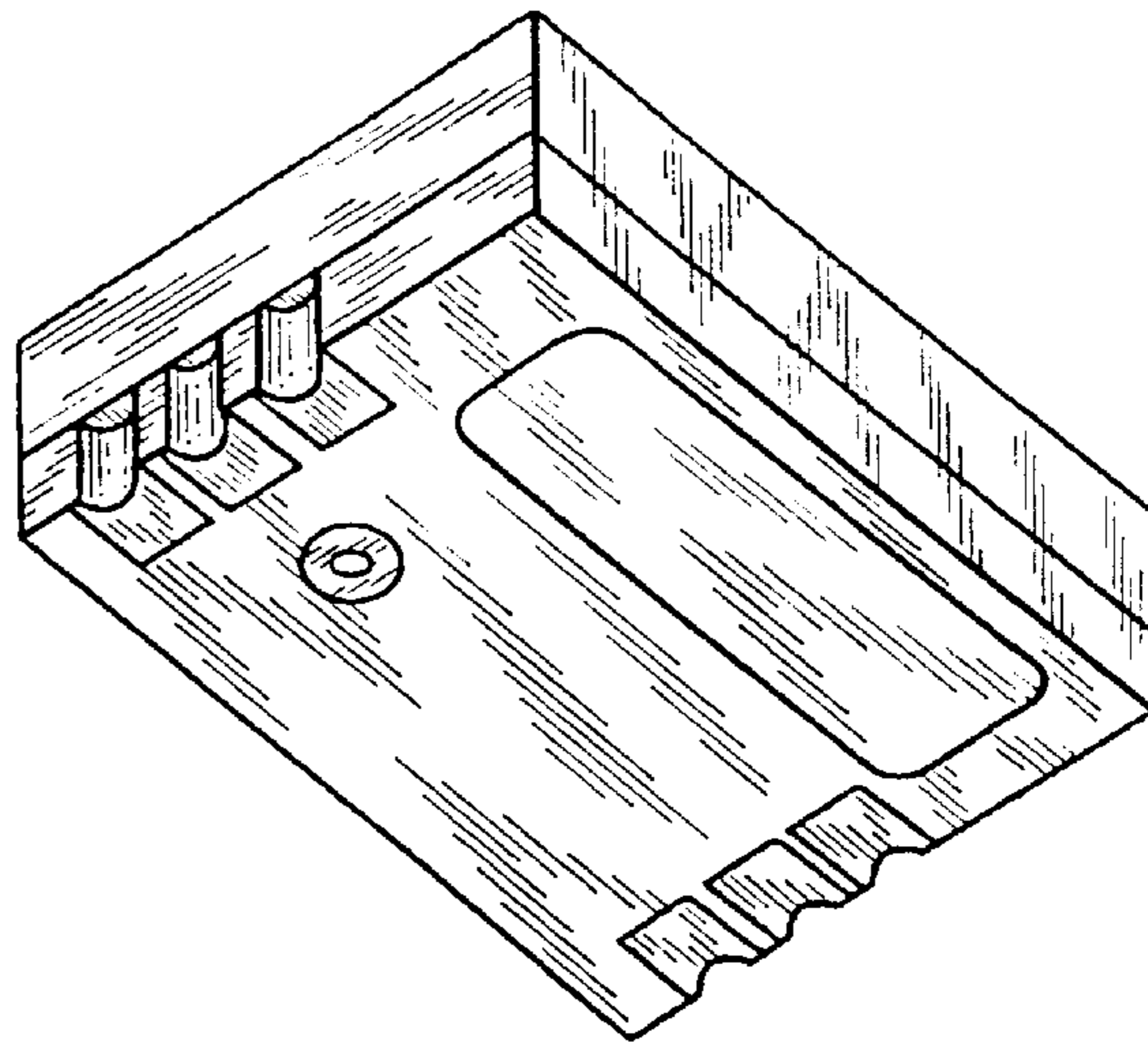
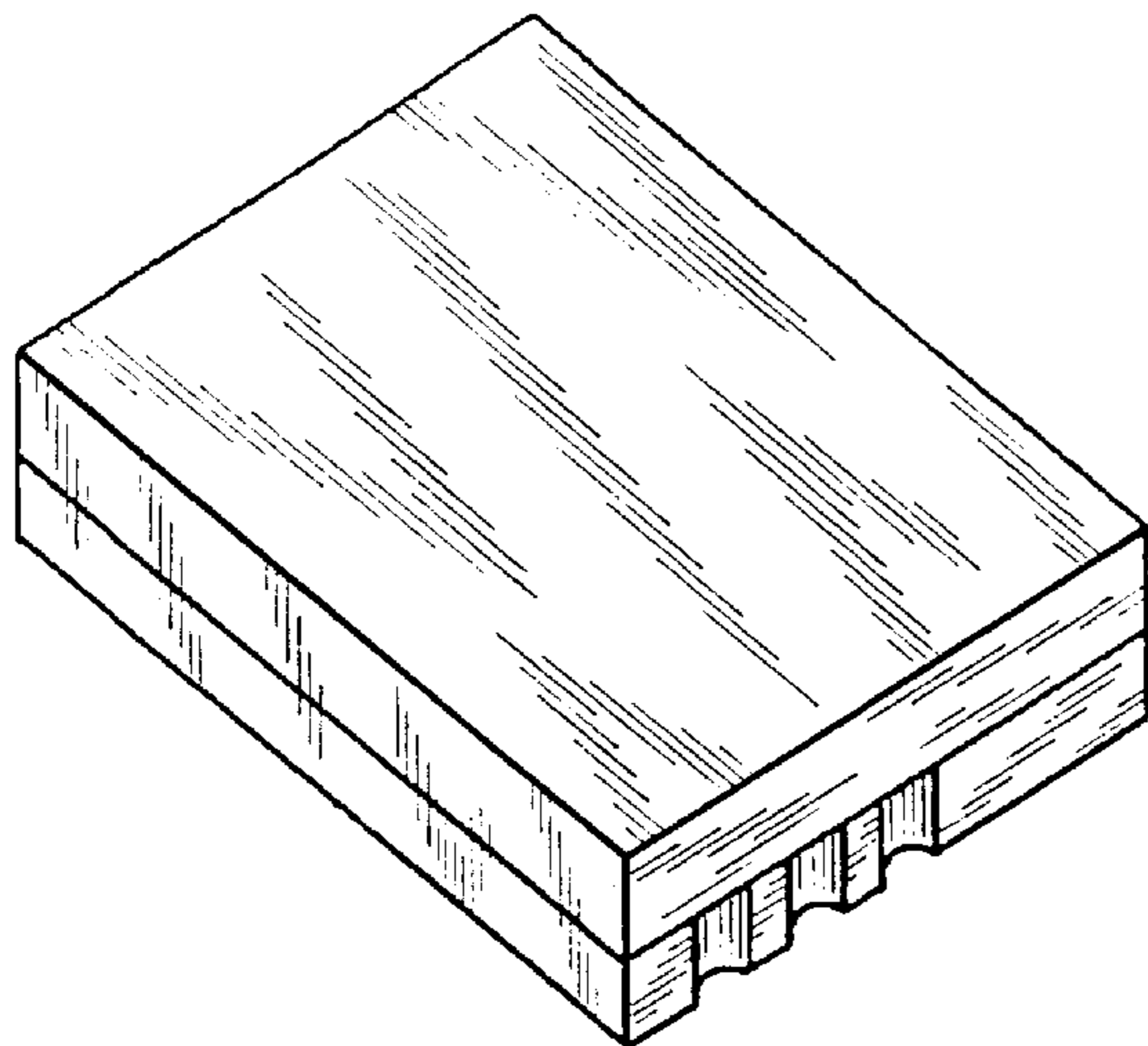
[57] **CLAIM**

The ornamental design for an integrated circuit package, as shown and described.

DESCRIPTION

FIG. 1 is a front elevational view of an integrated circuit package showing our new design; FIG. 2 is a top plan view thereof; FIG. 3 is a bottom plan view thereof; FIG. 4 is a right elevational view thereof, the left side being the same in appearance as the right side; FIG. 5 is a top, front, right perspective view thereof; and, FIG. 6 is a bottom, rear, right perspective view thereof.

1 Claim, 2 Drawing Sheets



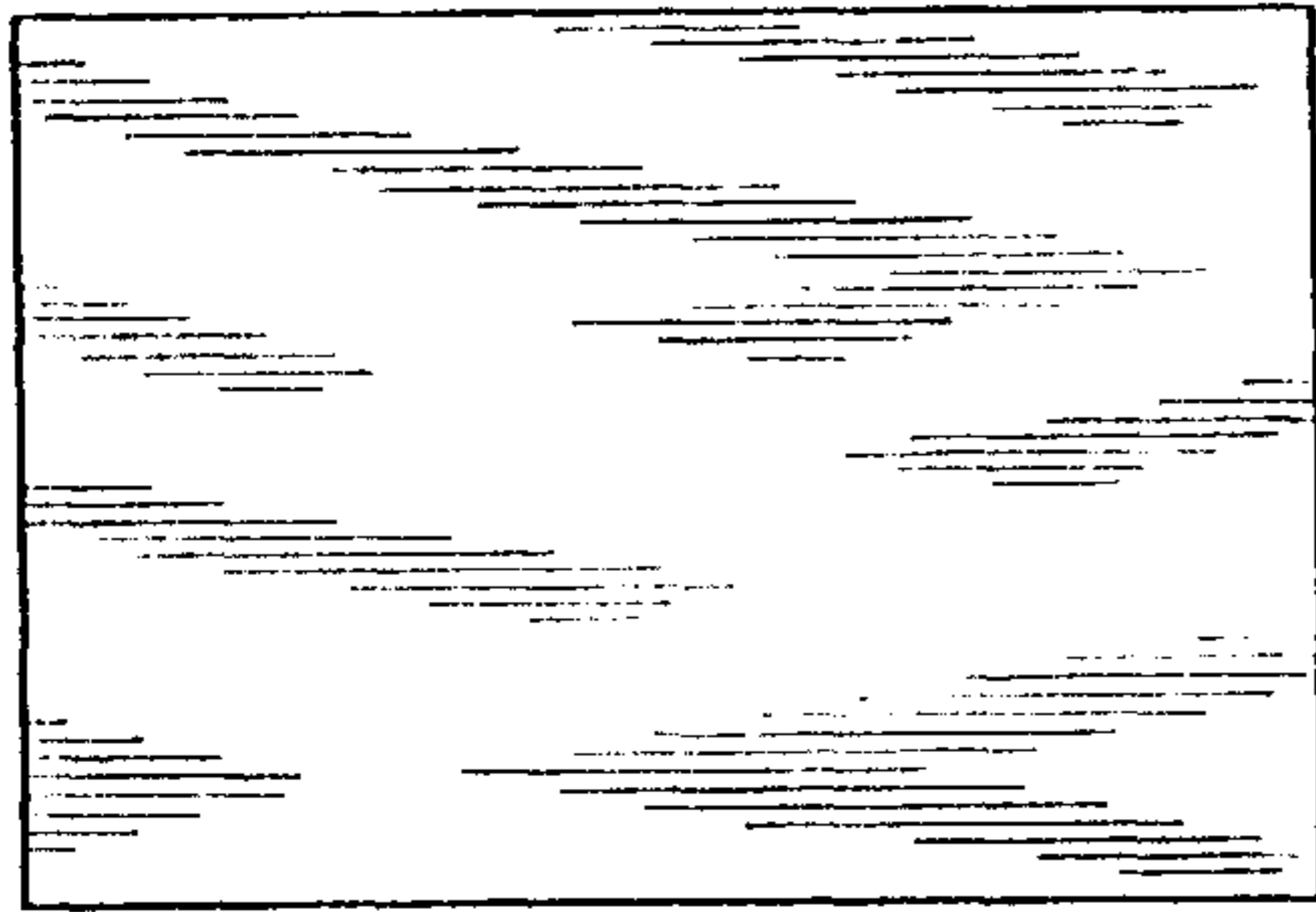


FIG. 2

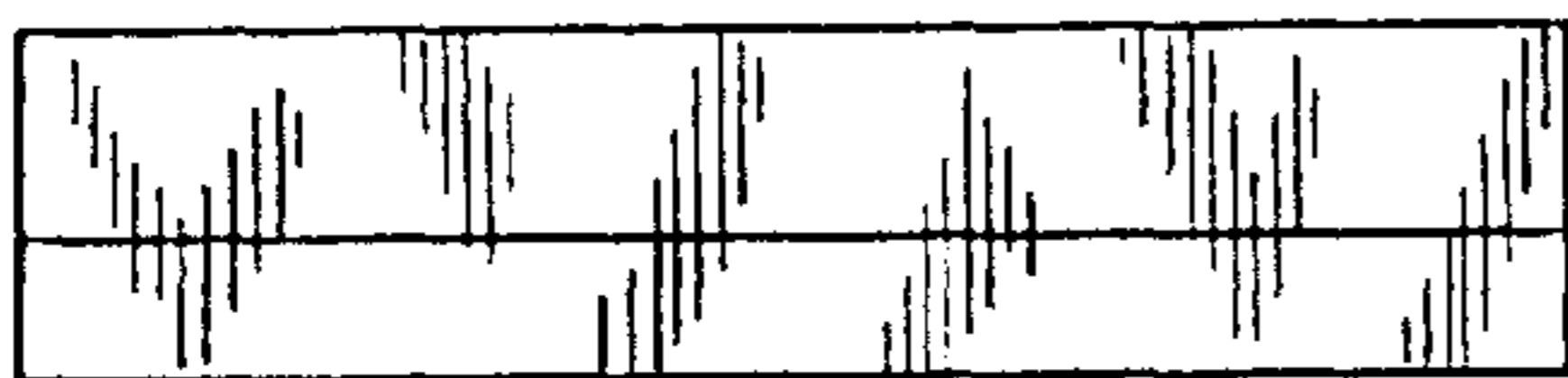


FIG. 1



FIG. 4

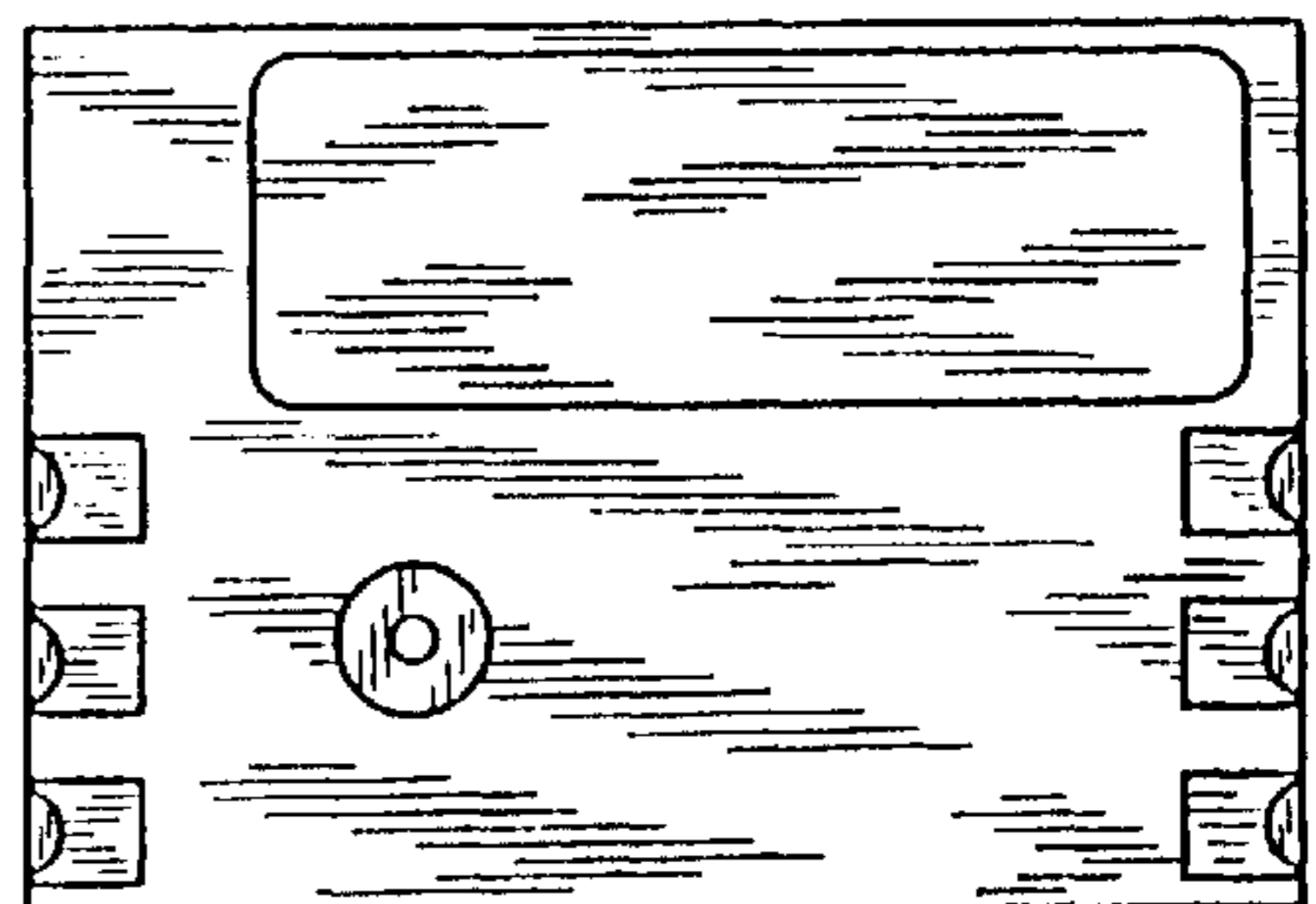


FIG. 3

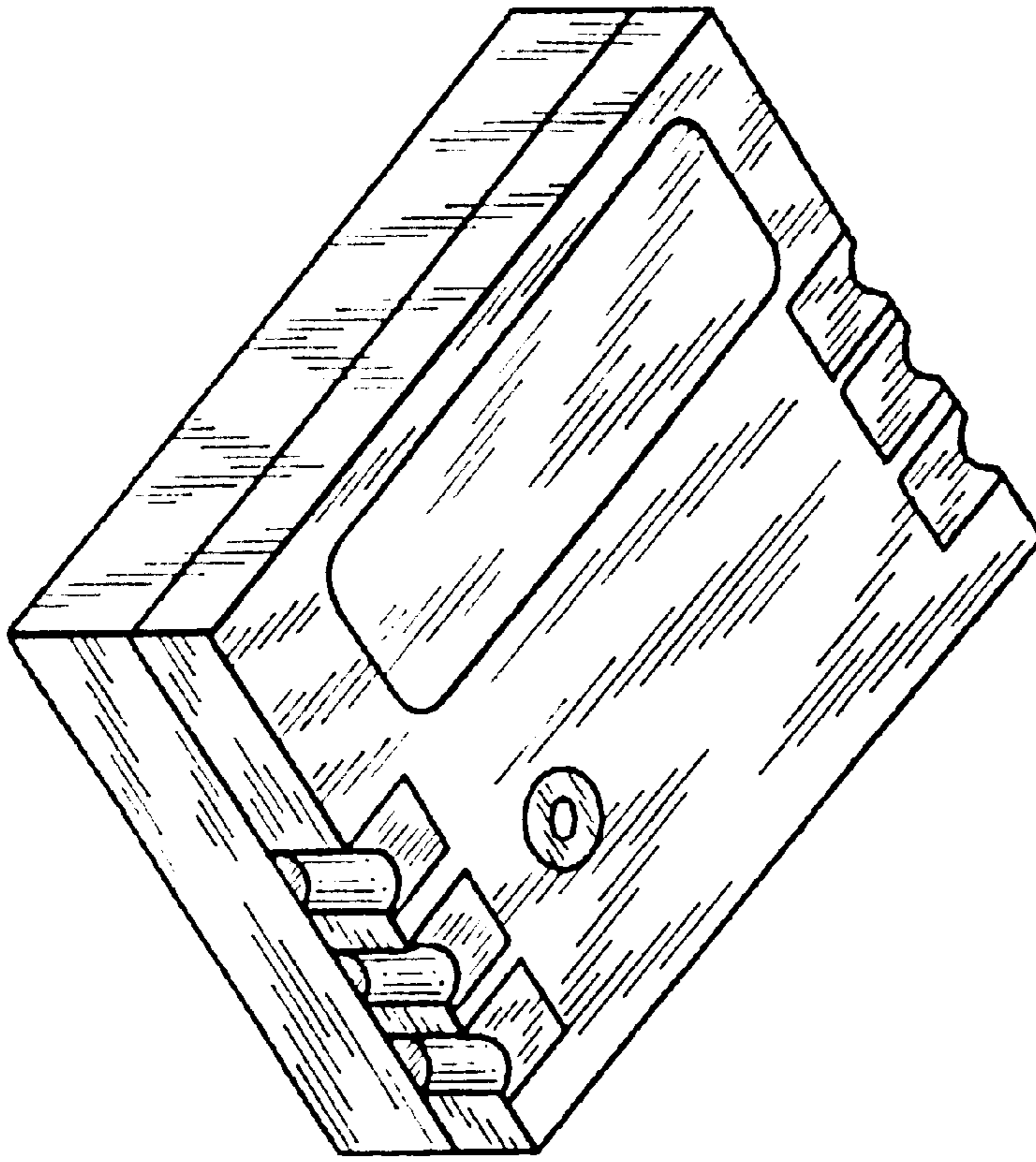


FIG. 5

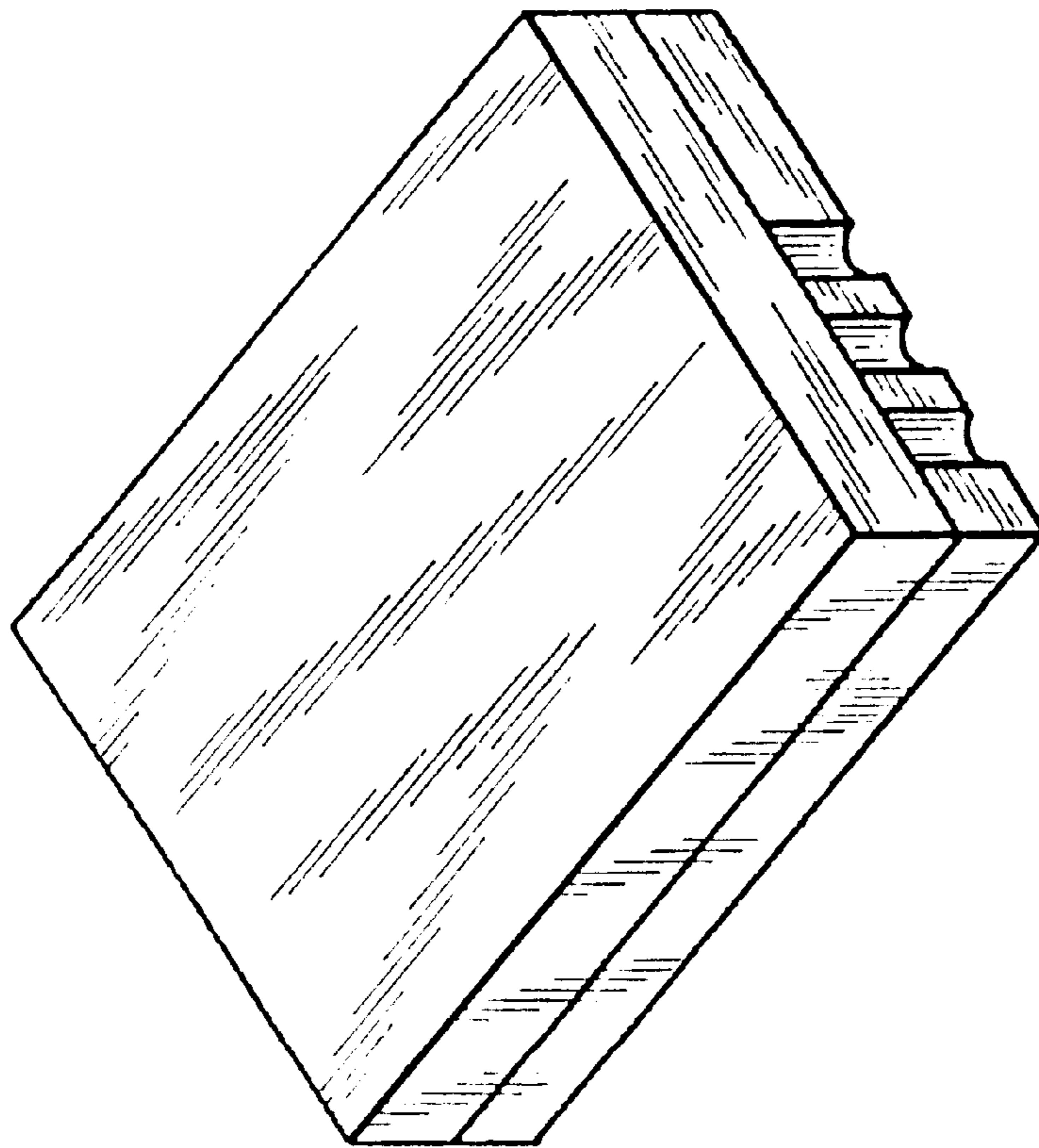


FIG. 6